Claims

1. A resin molding apparatus, comprising:

a resin supply mechanism configured to supply powder resin to a resin containing section including a release film and a frame placed on the release film; and

a resin collecting mechanism including a resin collector configured to suck the powder resin from the resin containing section for collection, and a film collector configured to collect the release film after the resin collector sucked the powder resin for collection.

2. The resin molding apparatus according to claim 1, wherein the resin supply mechanism supplies the powder resin on the release film, and

the resin collector is configured to suck the powder resin on the release film for collection.

3. The resin molding apparatus according to claim 2, further comprising:

a resin molding mechanism including a molding die that includes an upper die and a lower die facing the upper die and configured to place between the upper die and the lower die the release film with the powder resin on the release film for resin molding,

wherein the resin collecting mechanism is configured to suck the powder resin for collection before the release film is placed on the molding die.

4. The resin molding apparatus according to claim 3, wherein

the resin collecting mechanism includes:

a plate having a first hole and configured to cover, from above, the resin containing section, including the frame, from above to define a resin containing space together with the release film and the frame; and

a collection path having a first end connected to the first hole and a second end connected to a suction source;

a wherein the resin collector is connected to the second end.

5. The resin molding apparatus according to claim 4, wherein

the plate has at least one second hole connecting the resin containing space to an outside space to supply gas into the resin containing space.

6. The resin molding apparatus according to claim 5, wherein

the at least one second hole includes a plurality of second holes around the first hole.

7. The resin molding apparatus according to claim 5 or 6, wherein
the plate is configured to come into contact with the frame to cover the resin containing section from above.

8. The resin molding apparatus according to any one of claims 4 to 6, wherein
the plate is configured to cover the resin containing section from above with a gap between the frame and the plate.

9. The resin molding apparatus according to claim 1, further comprising a control section configured to determine whether the resin containing section received the powder resin appropriately,
wherein, if the control section determines that the powder resin has been received inappropriately, the resin collecting mechanism sucks the powder resin from the resin containing section for collection, and thereafter collects the release film.

10. A method for producing a resin molded product,
the method comprising:
supplying a predetermined amount of powder resin to a resin containing section including a release film and a frame on the release film;
determining whether the resin containing section has received the powder resin appropriately;
if it has been determined during the determining that the resin containing section has received the powder resin inappropriately, sucking the powder resin from the resin containing section for collection, and thereafter collecting the release film.

11. The method according to claim 10, wherein
the determining includes determining that the resin containing section has received the powder resin inappropriately if the resin containing section has received the powder resin (i) in an amount larger than the predetermined amount, (ii) at a flow rate higher than a threshold value, or (iii) with uneven distribution.